

6376611-1 ✓ ACTIVE

AMPMODU | [Micro Stack](#)

TE Internal #: 6376611-1

PCB Mount Header, Vertical, Board-to-Board, 80 Position, .6 mm [.023 in] Centerline, Partially Shrouded, Gold, Surface Mount, Signal, Micro Stack

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **80**

Centerline (Pitch): **.6 mm [.023 in]**

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Partially Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	80
Board-to-Board Configuration	Parallel

Electrical Characteristics

Operating Voltage	10 VAC
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Body Features

Primary Product Color	Black
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Contact Features

PCB Contact Termination Area Plating Material Thickness	.3 μ m[31.5 μ in]
PCB Contact Termination Area Plating Material	Gold Flash
Contact Base Material	Copper Alloy



Contact Mating Area Plating Material	Gold
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Contact Mating Area Plating Material Thickness	.3 μ m
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Contact Type	Pin
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Contact Current Rating (Max)	.5 A
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Termination Features

Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
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Rectangular Termination Post & Tail Width	1 mm[.04 in]
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Termination Method to Printed Circuit Board	Surface Mount
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Mechanical Attachment

PCB Mount Alignment Type	Solder Peg
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PCB Mount Retention Type	Solder Peg
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Mating Alignment	With
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Mating Alignment Type	Chamfered Edges
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PCB Mount Retention	With
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PCB Mount Alignment	With
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Connector Mounting Type	Board Mount
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Housing Features

Mating Entry Location	Top
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Centerline (Pitch)	.6 mm[.023 in]
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Housing Material	LCP (Liquid Crystal Polymer)
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Dimensions

Connector Height	6.75 mm[.265 in]
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PCB Thickness (Recommended)	1.6 mm
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Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application

Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	45
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Packaging Method	Tray
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Product Compliance

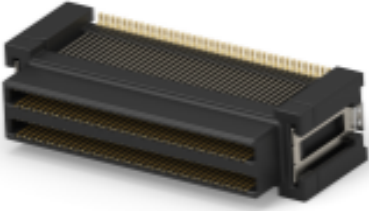

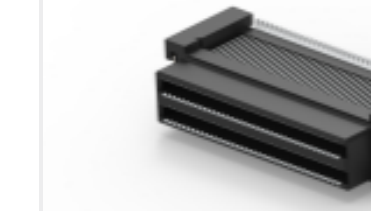

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

 <p>TE Part # 6376608-1 MICRO STACK REC ASSY 80P</p>	 <p>TE Part # 6376608-2 MICRO STACK REC ASSY 80P WITH TAPE</p>	 <p>TE Part # 6376608-3 MICRO STACK REC ASSY 80P</p>	 <p>TE Part # 6376608-4 MICRO STACK REC ASSY 80P WITH TAPE</p>
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Also in the Series | [Micro Stack](#)



Customers Also Bought



Documents

Product Drawings

[MICRO STACK HDR ASSY 80P H=6.75](#)

English

CAD Files

Customer View Model

[ENG_CVM_CVM_6376611-1_G.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_6376611-1_G.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_6376611-1_G.3d_stp.zip](#)



English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Product Specification

Japanese